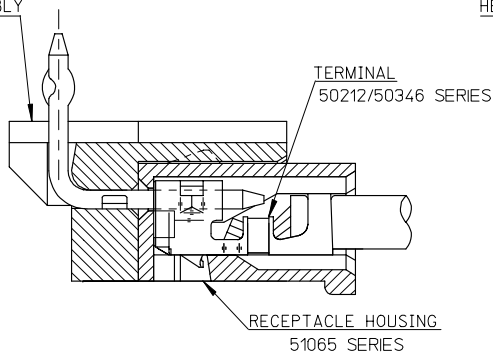


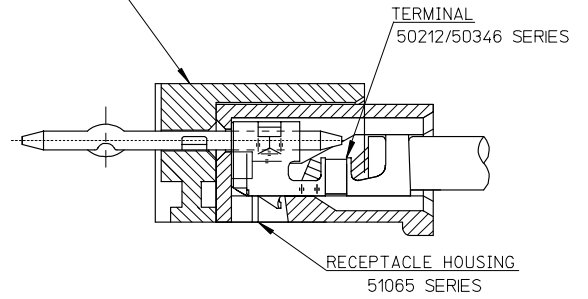
10 9 8 7 6 5 4 3 2 1

HEADER HOUSING ASSEMBLY  
53254SERIES

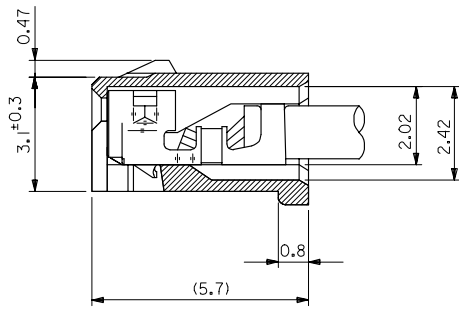


51065シリーズ/53254シリーズ 嵌合状態図 参考  
51065 SERIES/53254 SERIES MATED DRAWING (REF.)

HEADER HOUSING ASSEMBLY  
53253SERIES



51065シリーズ/53253シリーズ 嵌合状態図 参考  
51065 SERIES/53253 SERIES MATED DRAWING (REF.)



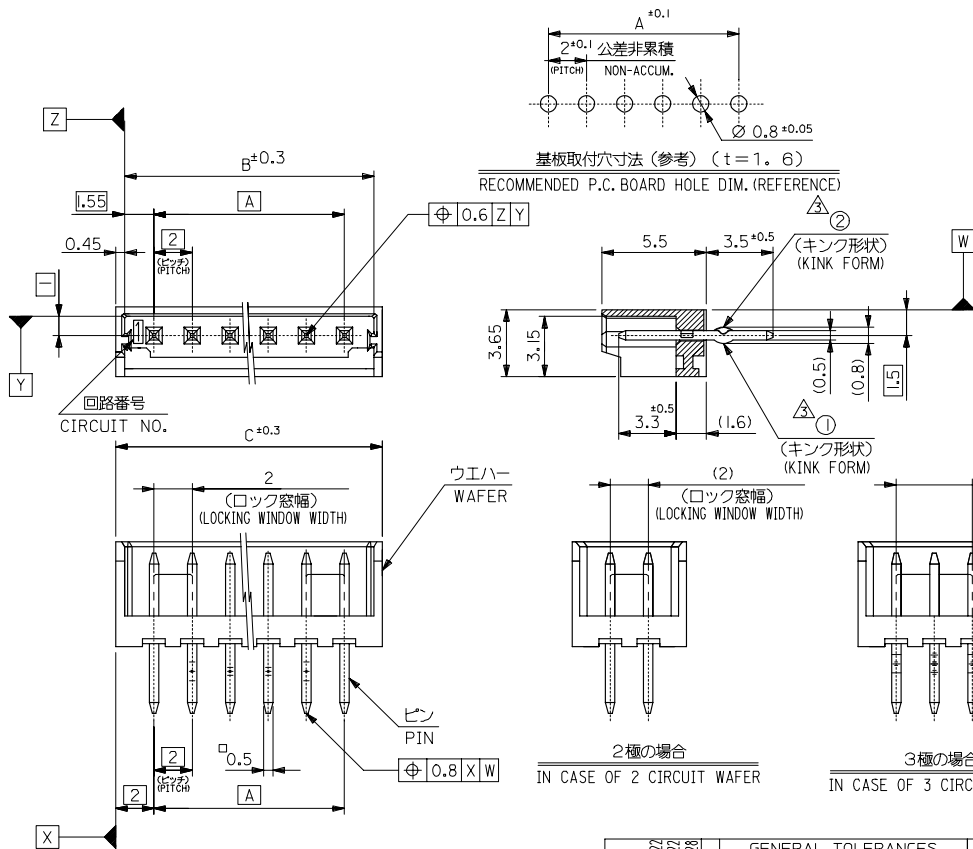
ターミナル装着状態図  
TERMINAL ASS'Y DWG.

RELEASED EC NO: J2008-2041 DRWN: AOYAGI 2007/11/13 CHKD: HARUYAMA 2007/11/22 APPR: NUKITA 2007/11/22	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY Y. AOYAGI	DATE 2007/11/13	TITLE NEW 2.0 W/B CONN. 51065/53253OR51065/53254  MOLEX INCORPORATED		
	10 OVER 30 UNDER	± 0.25	CHECKED BY N. UKITA	DATE 2007/11/13			
	30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 2007/11/13			
	ANGULAR	± 1 °	MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-51065-006	1 OF 1		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

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Rev. E 2006/04/15

9 8 7 6 5 4 3 2 1 EN-02JA(021)

10 9 8 7 6 5 4 3 2 1



注記 NOTES

1. 嵌合相手: 51065 シリーズ  
MATE WITH: 51065 SERIES
2. 材質 MATERIAL  
ウエハー: 66ナイロン, UL94V-0  
WAFER: 66NYLON, UL94V-0  
ピン: 黄銅, 錫メッキ  
PIN: BRASS, TIN(Sn) PLATING
- △ キングは下記表の位置及び形状に付加のこと。2極はキング無し。  
KINK TO BE APPLIED AS FOLLOWS,  
2 CIRCUIT HAS NO KINK.
4. 本製品は、53253-\*\*10の鉛フリー品です。  
THIS PRODUCT IS LEAD FREE OF 53253-\*\*10.
5. 梱包仕様 PACKAGING  
53253-\*\*70 トレー TRAY  
53253-\*\*50 ポリ袋 POLYBAG

極数 CKT	回路番号 CKT NO.	1	2	3	4	5	N-2	N-1	N
6 極以上	MORE THAN 6 CKT	—	①	②	—	—	②	①	—
5 極	5 CKT	①	②	—	②	①	—	—	—
4 極	4 CKT	①	②	①	—	—	—	—	—
3 極	3 CKT	①	②	①	—	—	—	—	—

32	31.1	28	53253-1550	53253-1570	15
30	29.1	26	-1450	-1470	14
28	27.1	24	-1350	-1370	13
26	25.1	22	-1250	-1270	12
24	23.1	20	-1150	-1170	11
22	21.1	18	-1050	-1070	10
20	19.1	16	-0950	-0970	9
18	17.1	14	-0850	-0870	8
16	15.1	12	-0750	-0770	7
14	13.1	10	-0650	-0670	6
12	11.1	8	-0550	-0570	5
10	9.1	6	-0450	-0470	4
8	7.1	4	-0350	-0370	3
6	5.1	2	53253-0250	53253-0270	2
C	B	A	MATERIAL NO.	MATERIAL NO.	極数
			MODEL NO. 53253-**70/**50		

REVISED IEC NO. J2005-2396 DRAWN BY CHIKUDA CHECKED BY CHIKUDA APPROVED BY APPR: NIKITA 2005/02/22 2005/02/22 2005/02/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. TSUBOI	DATE '04/01/15	TITLE NEW 2.0 WIRE TO BOARD CONN. WAFER ASSY (ST.) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY S. MARUYAMA	DATE '04/01/15	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/01/15	DOCUMENT NO. SD-53253-001		
	ANGULAR	±3 °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			